

#### **POWER MANAGEMENT**

# 20MHz, 650mA, X-EMI<sup>™</sup>-Enabled Synchronous Step-Down Regulator

#### **Features**

- Patented X-EMI<sup>TM</sup> Inductor Technology
  - Enables Trace Inductors in PC Board Material
  - Excellent EMI Performance
- Efficiency up to 90%
- 17.5µA Quiescent Current under Very Light Loads
- Wide Input Voltage Range 2.7V to 5.5V
- Adjustable Output Voltage Down to 1.0V
- Output DC Current up to 650mA
- High Light-load Efficiency via Automatic PSAVE Mode
- Ultra-fast Transient Response <1µs
- Temperature Range -40 to +85°C
- Shutdown Current 0.1µA (typical)
- Requires Tiny 220nH Inductor
- Requires Only 1µF of Output Capacitance
- External Switching Frequency Synchronization
- Protection Features Including
  - Over-Current Protection
  - Output Short-Circuit Protection
  - Thermal Shutdown Protection
- Offered in MLPD-UT 8 Lead Packages
- Lead-free, Halogen-free, and RoHS/WEEE Compliant

### **Applications**

- HDTV, Set Top Boxes, Gaming Consoles
- POL Applications
- White Goods

### **Description**

The SC221 is a 20MHz X-EMI<sup>™(1)</sup>-enabled step-down regulator optimized for power low voltage rails from 2.7 to 5.5V input voltage. X-EMI<sup>™</sup> inductor technology enables inductors to be drawn directly on the PC board. This technology meets or exceeds the EMI performance of chip inductors and eliminates the need for discrete inductors.

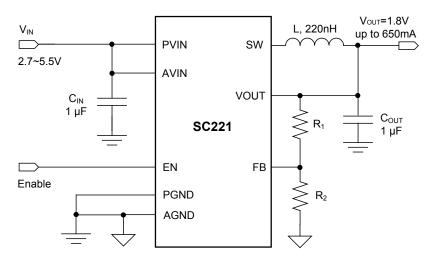
The SC221 uses a unique constant frequency, self-oscillating control loop architecture to provide excellent transient performance. Under light loads, the device operates in Power Save mode(PSAVE) maintaining a typical quiescent current of 17.5μA. At moderate to heavy loads, this part operates in PWM mode with a constant switching frequency of 20MHz. This high switching frequency offers the advantages of using small and low cost external components like a 1μF external capacitor and a small 220nH inductor (including X-EMI<sup>TM</sup> PCB trace inductors).

The device provides adjustable output voltages down to 1.0V and an output current up to 650mA. An EN pin can be used to synchronize to an external source and includes de-glitching to reduce noise sensitivity.

The SC221 is available in MLPD-UT 8 Lead package.

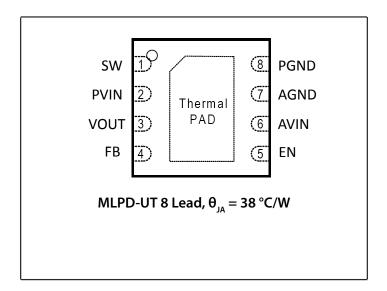
Note 1: Purchase of SC221 includes royalty-free right to use X-EMI  $^{TM}$  inductor technology with no additional cost.

## **Typical Application Circuit**





# **Pin Configuration**



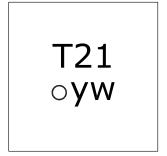
# **Ordering Information**

Device	Package
SC221ULTRT (1)(2)	MLPD-UT 8 Lead
SC221EVB	Evaluation Board

#### Notes:

- (1) Available in tape and reel only. A reel contains 3000 devices.
- (2) Device is lead-free, halogen-free, and RoHS/WEEE compliant.

# **Marking Information**



TOP MARK				
CHAR	ROWS			
3/3	2			



### **Absolute Maximum Ratings**

AVIN, PVIN (V)
VOUT, FB, EN, SW (V)0.3 to (V <sub>IN</sub> +0.3)
AGND (V)0.3 to +0.3
ESD Protection Level <sup>(1)</sup> (kV)

### **Recommended Operating Conditions**

Input Voltage Range (V)	+2.7	to	+5.5
Output DC Current (mA)	up	to	650
Operating Temperature Range (°C)	-40	to	+85

#### **Thermal Information**

Thermal Resistance, Junction to Ambient $\ensuremath{^{(2)}}$ (°C/W)38
Junction Temperature Range (°C) 40 to +150
Storage Temperature Range (°C)65 to +150
Lead Temperature (soldering 10s (°C)260

Exceeding the above specifications may result in permanent damage to the device or device malfunction. Operation outside of the parameters specified in the Electrical Characteristics section is not recommended.

#### Notes:

- (1) All voltage values in this section are with respect to PGND pin voltage.
- (2) Tested according to JEDEC standard JESD22-A114-B.
- (3) Calculated from package in still air, mounted to 3 x 4.5 (in), 4 layer FR4 PCB with thermal vias under the exposed pad per JESD51 standards.

#### **Electrical Characteristics -**

Unless otherwise specified: AVIN=PVIN = 3.6V, EN = AVIN = PVIN,  $C_{IN} = C_{OUT} = 1.0 \mu F$ , L=220nH.  $T_A = 25^{\circ}C$  for typical values, -40°C <  $T_A = T_J$  < 85°C for minimum and maximum values.

Parameter	Symbol	Condition	Min	Тур	Max	Units		
POWER SUPPLY	POWER SUPPLY							
Input Voltage	V <sub>IN</sub>		2.7		5.5	V		
Input Quiescent Current	I <sub>VIN_Q</sub>	No load, no switching		17.5	60	μΑ		
Shutdown Current	I <sub>VIN_SD</sub>	EN = 0V			1.0	μΑ		
POWER SWITCH			-					
PMOS On Resistance				400		mΩ		
NMOS On Resistance				360		mΩ		
OSCILLATOR								
Switching Frequency	f <sub>osc</sub>	PWM Mode	16	20	24	MHz		
REGULATION								
Output Voltage Tolerance(1)	V <sub>OUT_TOL</sub>		-4.0		4.0	%		
Current Limit	I <sub>LIMIT</sub>		800		1300	mA		
Soft-Start <sup>(1)</sup>	t <sub>ss</sub>	EN pin low to high		40		μs		
Feedback Voltage	V <sub>FB</sub>	2.7V ≤ VIN ≤ 5.5V	0.97	1.00	1.03	V		



# **Electrical Characteristics (continued)**

Unless otherwise specified: AVIN=PVIN = 3.6V, EN = AVIN = PVIN,  $C_{IN} = C_{OUT} = 1.0 \mu F$ , L=220nH.  $T_A = 25^{\circ}C$  for typical values, -40°C <  $T_A = T_J$  < 85°C for minimum and maximum values.

Parameter	Symbol	Condition	Min	Тур	Max	Units
Feedback Leakage Current	I <sub>FB</sub>				1	μΑ
ENABLE						
EN Input High Voltage Threshold	V <sub>ENH</sub>		1.2			V
EN Input "Low" Voltage Threshold	V <sub>ENL</sub>				0.4	V
EN Input High Current	I <sub>ENH</sub>	V <sub>EN</sub> = V <sub>IN</sub>	-1.0		1.0	μΑ
EN Input Low Current	I <sub>ENL</sub>	V <sub>EN</sub> = AGND	-1.0		1.0	μΑ
Minimum Synchronization Frequency	f <sub>SYN_MIN</sub>	Square wave applied at EN pin			3	MHz
PROTECTION						
Over Temp Thermal Shutdown <sup>(1)</sup>	T <sub>OT</sub>			150		°C
Thermal Shutdown Hysteresis <sup>(1)</sup>	T <sub>HYST</sub>			15		°C

#### Notes

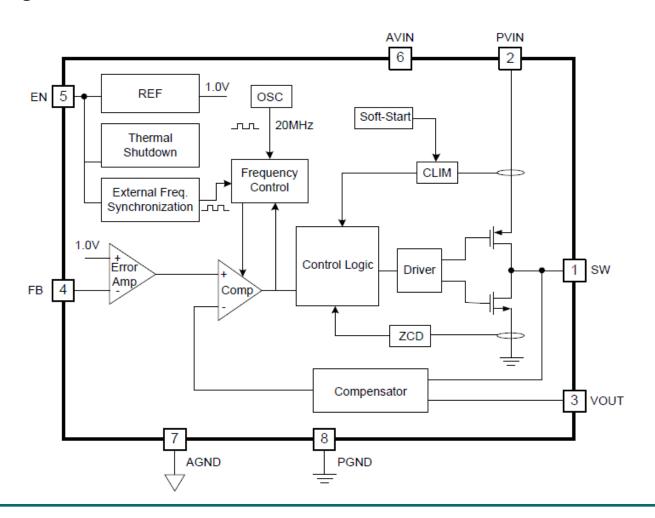
<sup>(1)</sup> Guaranteed by design. Not tested in production.



# **Pin Descriptions**

Pin #	Pin Name	Pin Function
1	SW	Switching output node — connect to the output LC filter.
2	PVIN	Power input supply voltage (2.7 to 5.5V).
3	VOUT	Input for sensing the output of LC filter.
4	FB	Input for regulation of output LC filter — Using $R_1$ and $R_2$ to set the output voltage, $V_{OUT} = V_{FB} \times (1 + R_1/R_2)$ . (Please refer to the typical application circuit diagram on page 1).
5	EN	Enable Input — when low, circuit draws $<1\mu$ A. Apply a square wave clock at EN to synchronize the switching frequency with an external clock. It is recommended that the externally applied clock frequency should not be above 20MHz.
6	AVIN	Input supply voltage
7	AGND	Analog ground
8	PGND	Power ground

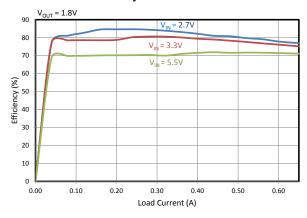
# **Block Diagram**



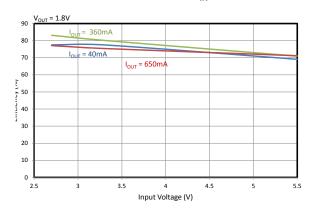


# **Typical Characteristics (Continuous)**

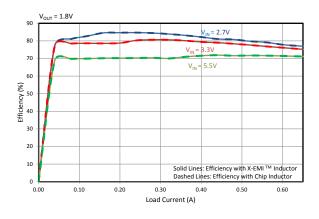
**Efficiency vs. Load Current** 



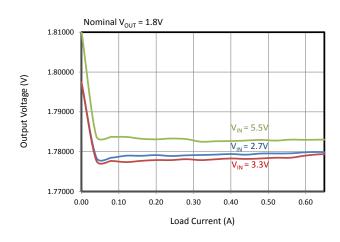
Efficiency vs. V<sub>IN</sub>



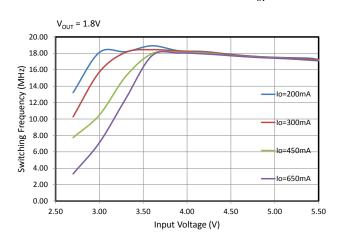
Efficiency vs. Load Current (Chip Inductor vs. X-EMI™ Inductor)



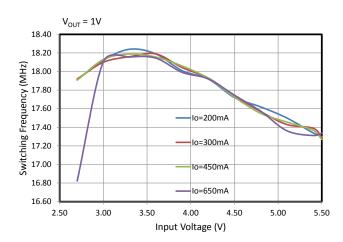
**Load Regulation** 



### Switching Frequency vs. V<sub>IN</sub>



### Switching Frequency vs. V<sub>IN</sub>

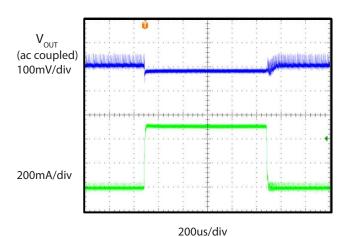




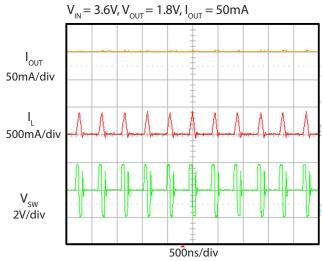
### **Typical Characteristics (Continuous)**

#### **Load Transient Response**

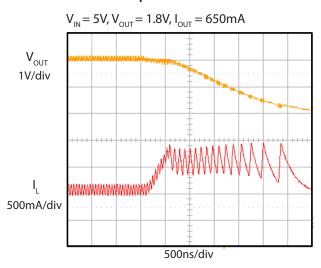
$$V_{IN} = 3.6V, V_{OUT} = 1.8V, I_{OUT} = 0mA - 500mA$$



# **Steady State Operation**

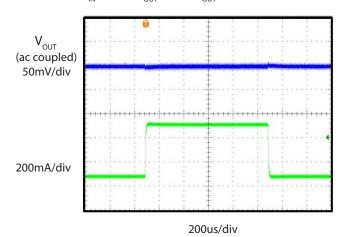


#### **Output Hard Short**

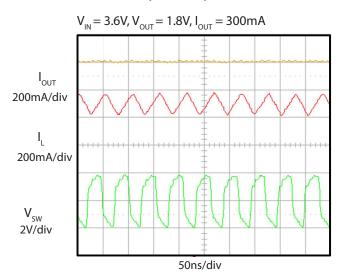


#### **Load Transient Response**

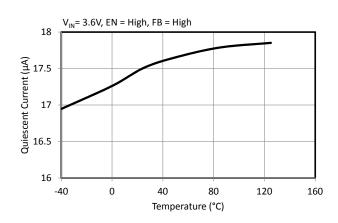
$$V_{IN} = 3.6V, V_{OUT} = 1.8V, I_{OUT} = 80mA - 500mA$$



#### **Steady State operation**



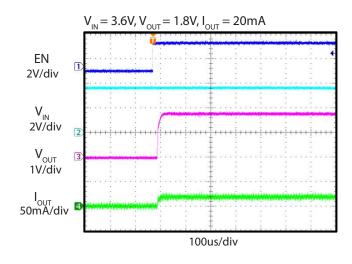
#### Input Quiescent Current vs. Temperature



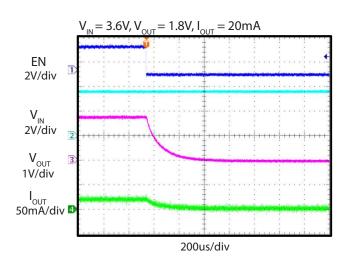


# **Typical Characteristics (Continuous)**

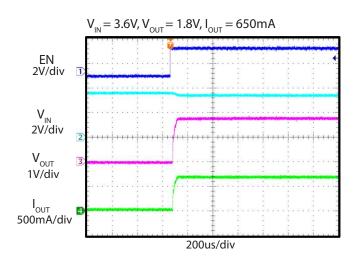
#### **Start-up Operation**



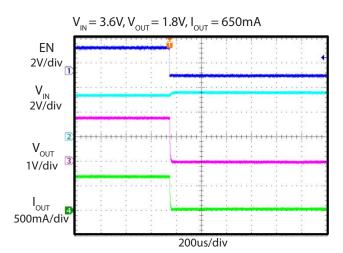
#### **Shutdown Operation**



#### **Start-up Operation**



#### **Shutdown Operation**





#### **General Description**

The SC221 is a step-down regulator capable of delivering a lower voltage from an input supply voltage of 2.7V to 5.5V with high efficiency. Using a unique control architecture, the SC221 is capable of delivering a peak efficiency upto 90%, while maintaining efficiency over 80% during light load condition. The converter operates at 20MHz switching frequency with pulse width modulation (PWM) at moderate to heavy loads up to 650mA. Under light load, the converter operates in power save (PSAVE) mode.

#### **Control Scheme**

The SC221 operates with a self-oscillating control method based on the output voltage ripple. This control loop compares the output voltage to an internal 1V reference to regulate the output voltage directly, adjusting the turn-on and turn-off time of the power switches such that the output voltage at the load is held at a precise value. This architecture gives a single-cycle response to transient events.

To maintain constant frequency, a phase locked loop (PLL) is included to synchronize the switching with an internal clock. This PLL adjusts the effective upper and lower thresholds of the comparator, thus maintaining a constant frequency. Under transient conditions the voltage control loop determines the required switching pattern to best maintain the output voltage. After a short transient, the PLL will bring the switching frequency back to normal. At extreme duty cycles, where the frequency control loop may not be able to maintain frequency lock even under steady-state conditions, frequency may fall, but the output voltage regulation will be maintained by the main voltage control loop. This unique architecture helps to achieve the excellent line and load transient response.

#### **Operating Modes**

The SC221 operates in two modes over a wide range of load currents. At moderate to high load, it operates in PWM mode with its switching frequency held constant. Under light loads, the converter enters PSAVE mode automatically. With the typical 220nH inductor, the transition between PWM and PSAVE mode typically occurs in the range of 100-200mA, depending on the input and output

voltages. At very light loads, the SC221 maintains high efficiency by shutting down all but the most essential circuit blocks, maintaining a typical quiescent current of about 17.5µA. In this mode, some circuitry used to control absolute DC accuracy is turned off. In that case, there may be a small DC shift (tens of mV) between normal operation and this 'no-load' state. However, in the case of a load transient, the system will turn on the high-side FET within nanoseconds as a discontinuous pulse is issued. The transition to PWM mode can occur within that nominal on-time, giving superior no load to full load transient response.

The transition from PWM mode to PSAVE mode is controlled by sensing the minimum value of the ripple current. When it drops below a threshold level for 32 consecutive cycles, the transition to PSAVE mode is initiated. Once in PSAVE, the regulation is maintained by modulating the time between fixed current pulses. When a new pulse is required by the loop before the existing pulse has terminated, the loop determines that the load cannot be maintained in PSAVE mode. This prompts an instantaneous switch from PSAVE mode back to PWM mode.

#### **Enable and Start-up**

The SC221 is enabled by applying a voltage higher than 1.2V on EN pin pin, and it is disabled when the applied voltage is pulled below the logic low threshold. The EN pin can also be used to set the switching frequency: if a digital clock is fed to EN, the SC221 will sense this as a valid enable signal and the external clock will be used rather than the internal 20MHz oscillator.

The SC221 has an internal soft start circuit that limits the inrush current during start-up with a stepped current limit. Over the course of about 40µs, the SC221 is stepped in increments of one quarter of the nominal current limit to full current limit, thereby reducing the worst-case surge current that might otherwise be reflected to the input current.

#### **Current Limit**

The SC221 integrates a current limit feature to protect itself and the external components during over load condition. When the current in the high-side PMOS switch exceeds the current limit, the PMOS switch is turned off.



### **Applications Information (Cont.)**

The high-side switch is then held off for a period sufficient to allow inductor current to decay. When the output voltage is close to the nominal regulation point, this will look similar to constant current limiting. As the output voltage falls, imposed off-time is such that the frequency will drop so that the inductor will have appropriate time to reset. This may cause the average current to reduce, giving a mild 'fold-back' characteristic to the current limit, where the average load current drops as the output voltage collapses (although the peak current maintains its nominal value). In a short-circuit condition, the system runs continuously at this reduced frequency.

#### **Load Transient Response**

The SC221 features excellent regulation during line and load transients. This is due to the nature of the proprietary control method and the high di/dt allowed by the use of a small inductor. This allows for best performance while providing the benefit of using a small low cost output capacitor.  $V_{\text{OUT}}$  shows only tens of milivolts of ripple voltage during a load current step change of 1mA to 650mA within hundreds of nanoseconds, using a 1µF output capacitor. (See the typical performance curves on page 7).

#### X-EMI™ Inductor Technology

The SC221 is the industry's first buck regulator that enables designers to draw their own inductors directly on the PC board. This patented technology is called as X-EMI™ inductor technology and is different from conventional PCB trace inductors. Conventional PCB trace inductors can be used with high-frequency switchers, but they exhibit significant EMI issues. X-EMI™ inductor technology solves these EMI problems and can meet or exceed the EMI performance of conventional chip inductors.



Figure 1. Top view of an evaluation board with X-EMI inductor

X-EMI<sup>™</sup> technology works by placing two small air-core inductors adjacent to one another in anti-phase position, where the magnetic fields of each inductor partially cancel one another to reduce EMI. The net flux from the two inductors, partially cancels the wide leakage paths caused by the wide geometry, while still storing the energy of the inductors in series. This approach uses multiple air core inductors implemented using printed circuit traces. Because these traces may be located on internal layers of the PCB, inductors can be designed with almost no impact on the available PCB area for components on the surface of the board. (See the efficiency curves using X-EMI<sup>™</sup> inductor technology on page 6).

#### **External Components**

The input and output capacitors used for the operation of the SC221 should be multilayer ceramic capacitors, preferably with X7R or X5R dielectric. SC221 is optimized to operate with the input and output capacitance of  $1\mu F$  typical. In practice, the self-resonant frequency of surface mount capacitors of this type is well below 20MHz ripple frequency, so efforts to minimize output ripple may best be focused on minimizing the inductance of the output capacitor and the length of the circuit path to ground rather than on increasing the capacitance value of the output capacitor.

The inductor should be a high current inductor rated for currents at least up to 1A. Typical power inductors may be too lossy at 20MHz unless specifically designed for high frequency operation. For inductor value of 220nH, it may be preferred to use wire-wound RF chokes, many of which are rated for appropriate currents.

#### Some Recommended External Components

	Value	Manufacturer	Part Number	Package
	0.22μΗ	Coilcraft	XFL2005-221ME	2x2mm
-	0.24μΗ	Coilcraft	0603LS-241XJL	0603
	0.22μΗ	Wurth Elektronik	74479762122	0603
CIN	1μF	Murata	GRM155R61C105KA12	0402
COUT	1μF	Murata	GRM155R61C105KA12	0402



### **Applications Information (Cont.)**

#### **PCB Layout Considerations**

Fundamental layout rules must be followed since the layout is critical for achieving the desirable performance.

Poor layout can degrade the performance of the DC-DC converter and can contribute to EMI problems, ground bounce, and resistive voltage losses, and possibly poor regulation and instability.

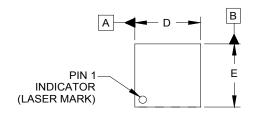
The following guidelines are recommended when developing a PCB layout:

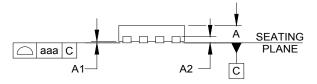
- 1. The input capacitor, C<sub>IN</sub> should be placed as close to the PVIN and PGND pins as possible. This capacitor provides a low impedance loop for the pulsed currents present at the buck converter's input. Use short wide traces to connect this capacitor as close to the IC as possible. This will minimize EMI and input voltage ripple by localizing the high frequency current pulses.
- 2. Keep the SW pin traces as short as possible to minimize

- pickup of high frequency switching edges to other parts of the circuit.  $C_{\rm OUT}$  and L should be connected as close as possible between the SW and GND pins, with a direct return to the GND pin from  $C_{\rm OUT}$ .
- Route the output voltage feedback/sense path away from the inductor and SW node to minimize noise and magnetic interference to the output feedback/ sense path.
- 4. Use a ground plane referenced to the PGND pin, and the ground connection of the input and output capacitors should be put on this plane and close to each other if possible, and as close to the PGND pin as possible. Use several vias to connect to the component side ground to further reduce noise and interference on sensitive circuit nodes.
- 5. If possible, minimize the resistance from the VOUT and AGND pin to the load. This will reduce the voltage drop on the ground plane and improve the load regulation. And it will also improve the overall efficiency by reducing the copper losses on the output and ground planes.

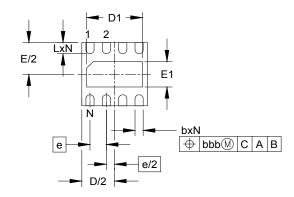


### **Outline Drawing — MLPD-UT 8 Lead**





	DIMENSIONS					
DIM	INCHES			MILLIMETERS		
ווווטן	MIN	NOM	MAX	MIN	NOM	MAX
Α	.020	-	.024	0.50	-	0.60
A1	.000	-	.002	0.00	-	0.05
A2		(.006)		(	0.1524	.)
b	.007	.010	.012	0.18	0.25	0.30
D	.075	.079	.083	1.90	2.00	2.10
D1	.061	.067	.071	1.55	1.70	1.80
Е	.075	.079	.083	1.90	2.00	2.10
E1	.026	.031	.035	0.65	0.80	0.90
е	.020 BSC			0	.50 BS	С
L	.012	.014	.016	0.30	0.35	0.40
N	8				8	
aaa	.003			0.08		
bbb	.004				0.10	

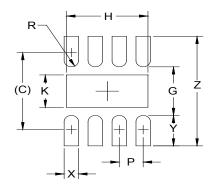


#### NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.



### Land Pattern — MLPD-UT 8 Lead



	DIMENSIONS						
DIM	INCHES	MILLIMETERS					
С	(.077)	(1.95)					
G	.047	1.20					
Н	.067	1.70					
K	.031	0.80					
Р	.020	0.50					
R	.006	0.15					
X	.012	0.30					
Υ	.030	0.75					
Z	.106	2.70					

#### NOTES:

- 1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
- 2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY. CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.
- 3. THERMAL VIAS IN THE LAND PATTERN OF THE EXPOSED PAD SHALL BE CONNECTED TO A SYSTEM GROUND PLANE. FAILURE TO DO SO MAY COMPROMISE THE THERMAL AND/OR FUNCTIONAL PERFORMANCE OF THE DEVICE.